

IEEE Open Access Workflow for Authors (Touch-Free)

OA only journals



Author Process

Submission, acceptance, and seeking funding

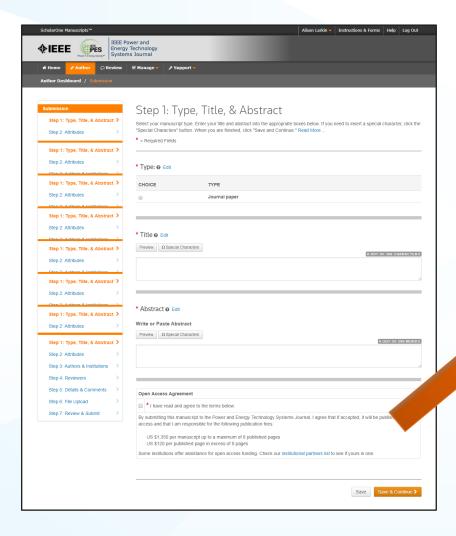


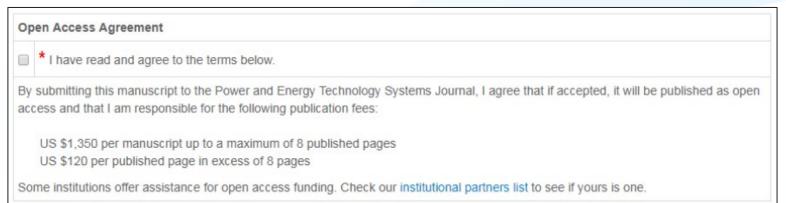
Submission process

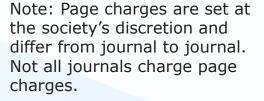
- The corresponding author will complete the submission process.
- Authors submitting to fully OA journals will be asked to accept Open Access terms and charges during the first step of the submission process.



Submission - OA journal





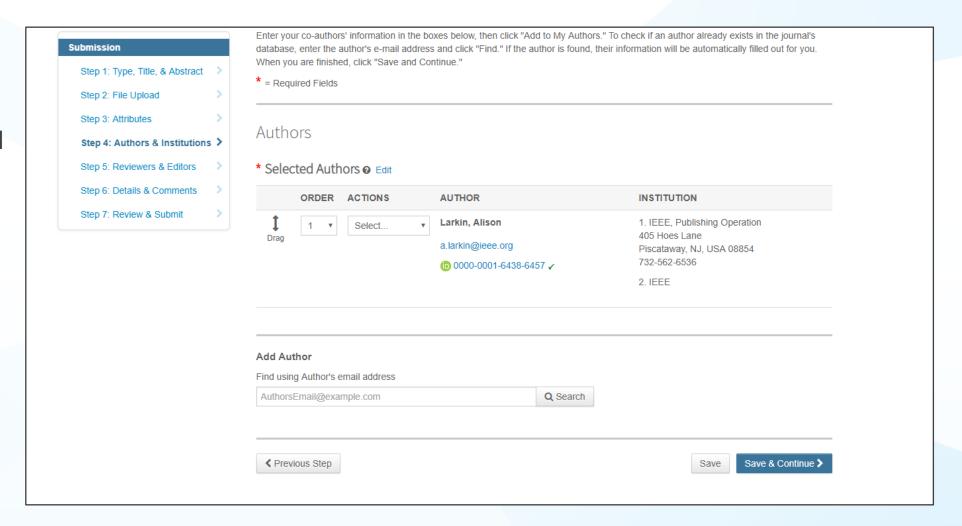




Submission

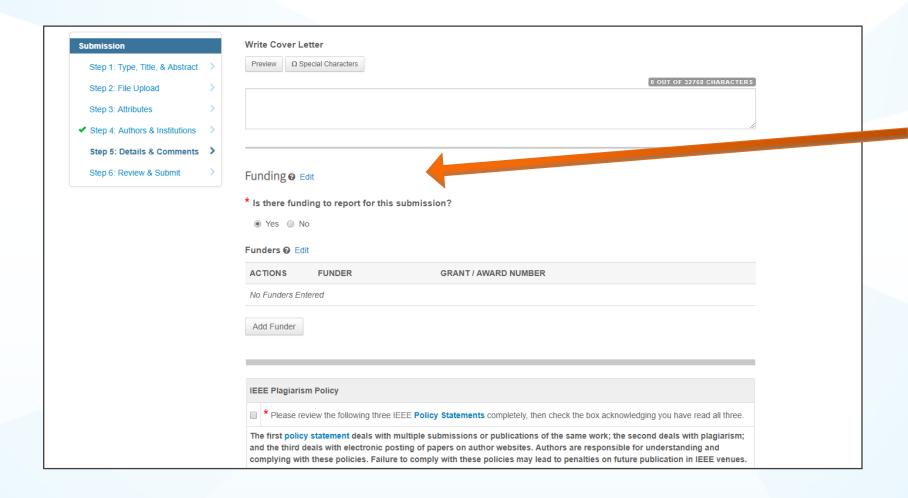
The corresponding author adds affiliation data for all authors.

The institution data entered here will be used to match the author with an institutional OA account.





Submission – Details & Comments



Authors will also be asked to enter their funding information. (The exact location of this question differs from journal to journal)

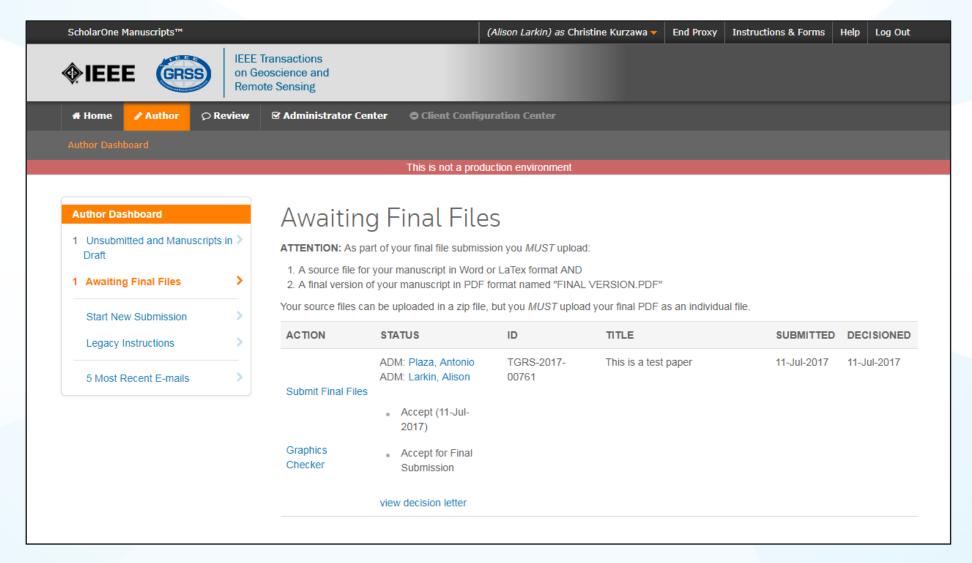


Acceptance

If the manuscript is accepted, the author will be prompted to upload the final files and choose a copyright license.



Post acceptance – final files upload





Post acceptance – copyright selection

After acceptance, authors will be prompted to choose their copyright license using the **Electronic Copyright Form** (eCF).

- Authors publishing in gold journals may choose between CCBY or CCBY NC-ND :
 - A CC BY 4.0 license (in which the author retains copyright and the article is published open access).
 - A CC BY NC-ND license (a more restrictive license than CCBY in that the article may not be reused for commercial purposes, nor may the article be changed in any way.)

Authors should confirm any license restrictions set by the institution.



Electronic Copyright Form (eCF)

- 1. Confirm that the article details are correct.
- Confirm the paper's originality
- OA Authors must agree
 "to pay" an APC
 (Article Processing
 Charge)
- 4. Select and sign CCBY license type
- 5. Download a copy of the agreement





RightsLink for Scientific Communications (RLSC)

- All article processing charges (APCs) are handled through RLSC.
- After acceptance, RLSC will generate a funding request for the institution (if the author is affiliated with an institution that has OA agreement).
 - Institutional profiles are matched using author-provided affiliation data and Ringgold IDs.
 - In some cases, the author's email domain may also be used as a matching criterion.

Authors do not need to request funding through RLSC as this is done when a match is made between the manuscript metadata and the institution's profile in RLSC

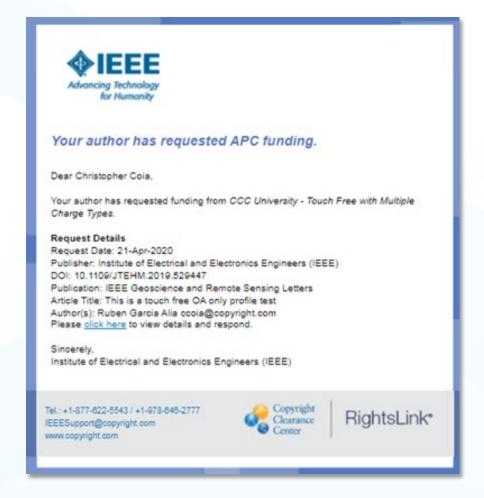


Account Administrator capabilities

- The Institution Portal in RightsLink for Scientific Communications (RLSC) allows administrators to:
 - View pending transactions.
 - Approve or deny funding requests.
 - Manage notifications.
 - Pull transaction reports.
- Administrators can also set Xplore alerts to monitor published articles.



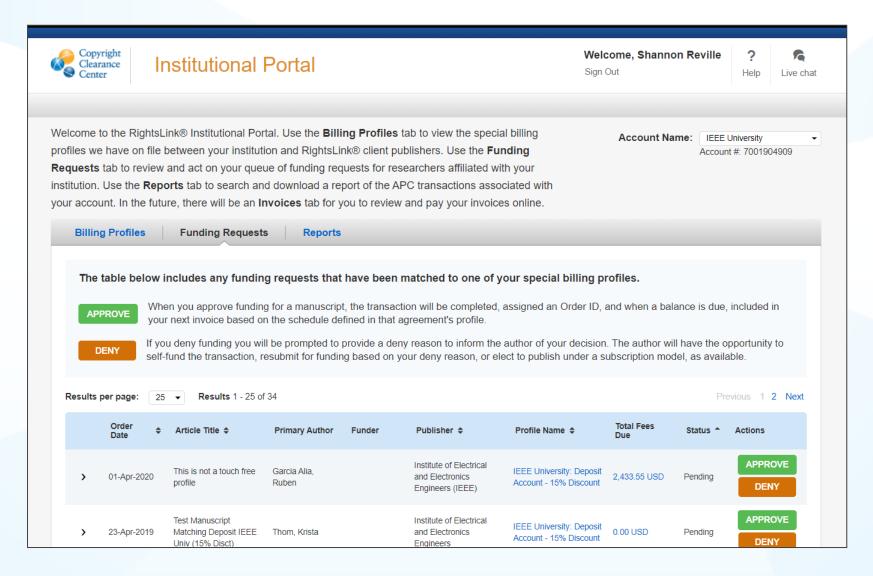
Notifications



Administrators will receive an email



Account dashboard



When administrators log in, they will be able to view and respond to outstanding requests.



Responding to funding requests

	Order \$	Artic	le Title ≑	Primary Author	Funder	Publisher \$	Profile Name ♦	Total Fees	Status ^	Actions
	Date							Due		
~	01-Apr-2020	This is	s not a touch free	Garcia Alia, Ruben		Institute of Electrical and Electronics Engineers (IEEE)	IEEE University: Deposit Account - 15% Discount	2,433.55 USD	Pending	APPROVE
	Tali, Maris; Cecchetto, Matteo; Cerutti, Francesco; Coronetti, Andrea; Danzeca, Salvatore; Esposito, Luigi; F Angelo; Kastriotou, Maria; KERBOUB, Nourdine; Lerner, Giuseppe; Wyrwoll, Vanessa; Ferlet-Cavrois, Veror Heikki; Garcia, Yolanda; MARTIN-HOLGADO, PEDRO; Gaillard, Remi; Wrobel, Frederic; Cazzaniga, Carlo; Helmut; Brugger, Markus								ar; Javanainen,	Arto; Kettunen,
	Journal		IEEE Geoscience	and Remote Sensing	Letters					
	DOI		10.1109/JTEHM.2	019.294557						
	License		CC BY							
	Manuscript Ty	Manuscript Type								
	Submission D	Submission Date								
	Acceptance Date		01-Apr-2020							
>	23-Apr-2019	Test Manuscript 23-Apr-2019 Matching Deposit Univ (15% Disct)		Thom, Krista		Institute of Electrical and Electronics Engineers	IEEE University: Deposit Account - 15% Discount	0.00 USD	Pending	APPROVE DENY
>	23-Apr-2019	Match	Manuscript ning Deposit IEEE (15% Disct)	Thom, Krista		Institute of Electrical and Electronics Engineers	IEEE University: Deposit Account - 15% Discount	0.00 USD	Pending	APPROVE

Pending articles will be shown at the top of the page by default.

Clicking the number in the "Total Fees" column will bring up the order confirmation page with manuscript details.

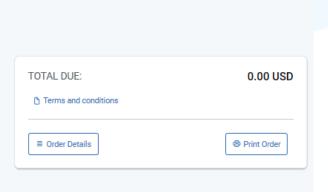


Manuscript details page

PAY AUTHOR CHARGES FOR "10-60 GHz Electromechanical Resonators using Thin-film Lithium Niobate" Author: Yansong Yang Manuscript ID: TMTT-2020-06-0629 Order Confirmation Thank you for submitting your funding request! Your request is now under review by your Institution. How will I know if my request is approved? How will I know if my request is denied? Order number: Not available until funding is approved. Order date: 06-Oct-2020 Tell us how we're doing! How was your experience? Click here to give us your feedback! Your Tools & Services RightsLink ® Manage Account View Orders and Download/Pay Invoices

Log in to RightsLink Manage Account - where you view your orders, download invoices, pay invoices by

credit card and more.



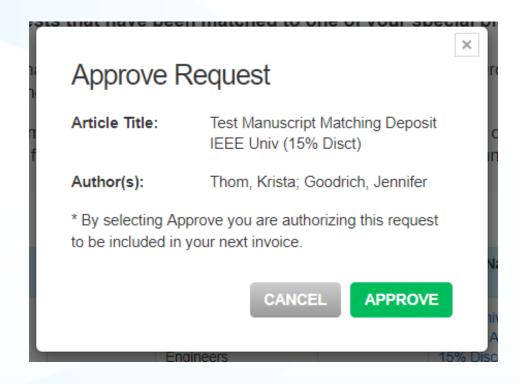
Manuscript Details

The detailed order confirmation page is available to both authors and administrators.

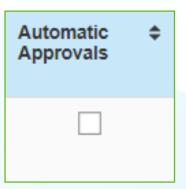
It includes information on article license type, discounts, and pricing.



Approving requests

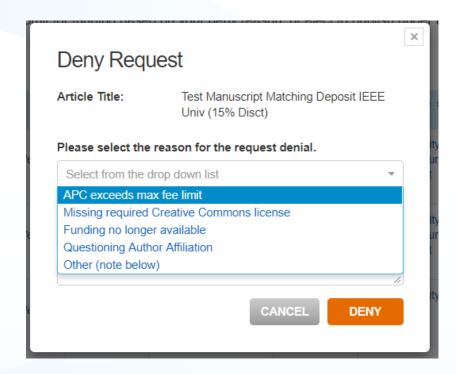


Clicking "Approve" will launch a popup box that prompts the administrator to confirm approval. Administrators can also choose to approve requests automatically under the "Billing Profiles" tab.



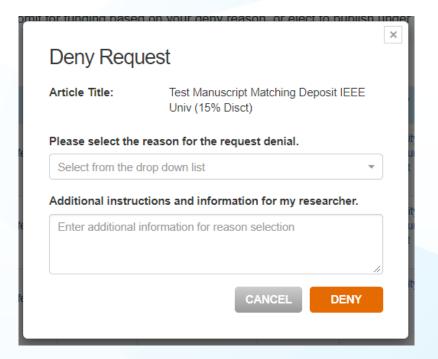


Denying requests



If a funding request is denied, administrators can select the reason from the pre-populated dropdown list. The reason will be included in the notification email sent to the author.

Administrators can also add an explanation or further instructions. (If "Other" is selected from the dropdown menu, this field is mandatory.)





Article Acceptance

The author receives an email when the request is approved or denied by the institution.



Your article has been accepted and will be published open access

Dear Mr. Ruben Garcia Alia.

Congratulations on being accepted for publication in IEEE Geoscience and Remote Sensing Letters for the following manuscript:

Manuscript DOI: 10.1109/JTEHM.2019.529447

Manuscript ID: TNS-003417-445

Manuscript Title: This is a touch free OA only profile test

Published by: Institute of Electrical and Electronics Engineers (IEEE)

Total Charges Covered: 2045.00 USD

Funding for your open access publication charges has been covered by CCC University based on an agreement between CCC University and Institute of Electrical and Electronics Engineers (IEEE).

If there are any additional publication charges available to you, such as page or color charges, we will send a payment link for those charges under separate cover.

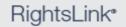
Sincerely.

Institute of Electrical and Electronics Engineers (IEEE)

Tel.: +1-877-622-5543 / +1-978-646-2777

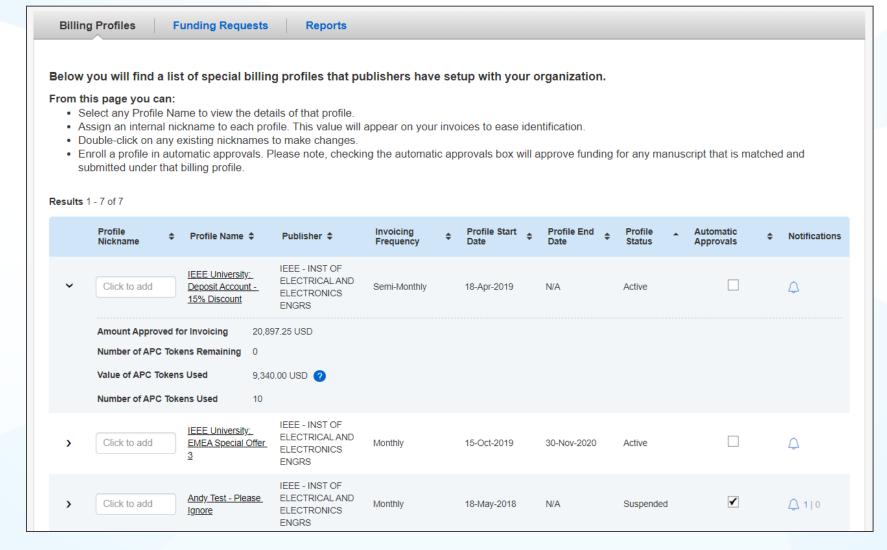
IEEESupport@copyright.com www.copyright.com







Billing Profiles

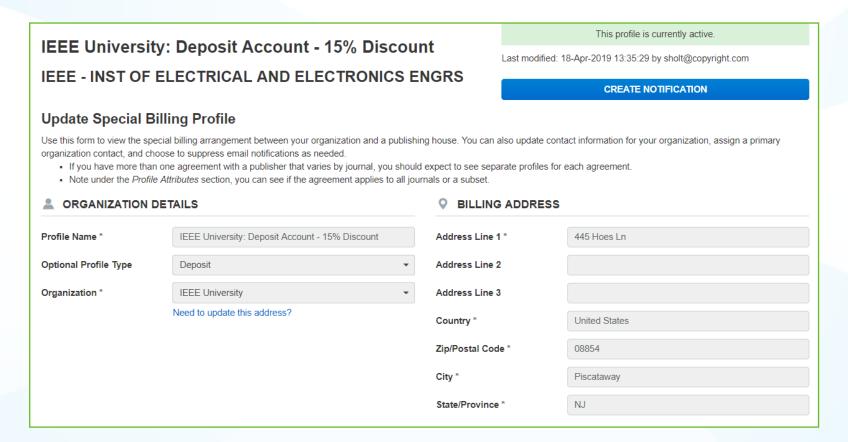


If an institution has agreements with multiple publishers that use RLSC, they will be able to access all profiles from the "Billing Profiles" tab.

Administrators can also set automatic approvals, manage notifications, and view agreement details.



Billing Profiles



Clicking on a specific profile will bring up agreement details.

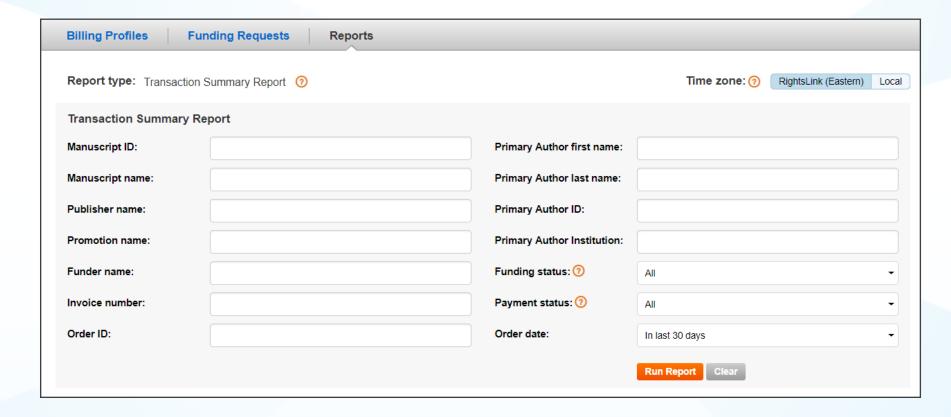
Most of the data will be read-only. However, administrators can add contacts, manage notifications, add a special note to authors, and choose to require an order number.



Reporting



Reports

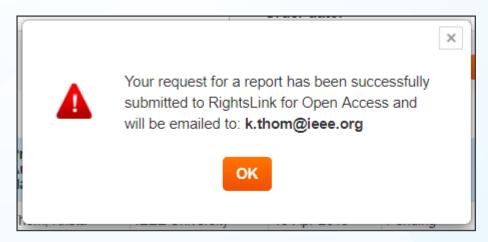


In the "Reports"
tab,
administrators
can run
Transaction
Summary Reports
based on various
criteria.



Reports

- If an institution has profiles with multiple publishers, manuscripts from all publishers will be shown by default. However, it is also possible to limit results to a single publisher.
- Transaction Summary Report data is refreshed hourly.
- Full reports will be sent by email.





Important questions to check

- With "Touch Free" workflow the "Bill me" option is only available if admin has denied the funding
- Additional reports about articles published traditionally (closed) are included in a different report and can be shared quarterly



Choosing Where to Submit

■ IEEE Publication Recommender helps authors find the most suitable journal and displays journal's OA Status with submission URL

IEEE Publication Recommender[™] **∲IEEE** Find the best match for your scholarly article Get all the key data about IEEE publications at a glance Search 190+ periodicals and 1800+ conferences · Compare critical points such as Impact Factor and · Download the results of your search Submission-To-Publication Time **IEEE** Publication Recommender **♦**IEEE Choose a search type and let Publication Recommender do the work! Periodical: Electron Devices Society, IEEE Journal of the Extract keywords Enter keywords, key phrases, or article title Both Periodicals and Conferences Impact Factor: Open Access Availability: Open Access Electron Devices Periodicals only Eigenfactor: 0.00259 Submission to Publication in Xplore: Not yet Conferences only **Article Influence Score: ②** 0.764 available Issues per year: 1 PERIODICALS Electron Devices, IEEE Transactions on Narrow by date: Published By: Not vet available I wo Electron Devices Society, IEEE Journal of the (Optional) Electron Device Letters, IEEE The IEEE Journal of the Electron Devices Society (J-EDS) is an open-Go to https://ieeexplore.ieee.org/xpl/RecentIssue.jsp?punu access, fully electronic scientific journal publishing papers ranging from Periodical mber=6245494 fundamental to applied research that are scientifically rigorous and home page: relevant to electron devices. The J-EDS publishes original and significant 2020 IEEE International Electron Devices Meeting contributions relating to the theory, modelling, design, performance, Contact: Not yet available (IEDM) and reliability of electron and ion integrated circuit devices and Or, find details for a specifi 2021 IEEE International Electron Devices Meeting (IEDM) Enter the name of a periodical or conference 2023 International Electron Devices Meeting (IEDM) 2022 International Electron Devices Meeting (IEDM) 2024 IEEE International Electron Devices Meeting

Note: Open Access status clearly displayed in results.

Need additional assistance?

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- Author posting guidelines
 - https://www.ieee.org/publications/rights/author-posting-policy.html

